Power MOSFET

60 V, 300 mA, Dual N-Channel with ESD Protection, SC-88

Features

- Low R_{DS(on)}
- Low Gate Threshold
- Low Input Capacitance
- ESD Protected Gate
- NVJD Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- This is a Pb-Free Device

Applications

- Low Side Load Switch
- DC-DC Converters (Buck and Boost Circuits)

MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Parame	Symbol	Value	Unit			
Drain-to-Source Voltage			V _{DSS}	60	V	
Gate-to-Source Voltage			V _{GS}	±20	V	
Continuous Drain	Steady	T _A = 25°C	I _D	300	mA	
Current (Note 1)	State	T _A = 85°C		233		
	t ≤ 5 s	T _A = 25°C		310		
		T _A = 85°C		240		
Power Dissipation (Note 1)			P _D	300	mW	
	t ≤ 5 s			319		
Pulsed Drain Current	t _p =	= 10 μs	I _{DM}	1200	mA	
Operating Junction and S	T _J , T _{STG}	–55 to 175	°C			
Source Current (Body Did	I _S	250	mA			
Lead Temperature for Sol (1/8" from case for 10 s)	T _L	260	°C			
Gate-Source ESD Rating	ESD _{HBM}	2000	V			
Gate-Source ESD Rating	ESD _{MM}	200	V			

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Ambient - Steady State	$R_{\theta JA}$	500	°C/W
Junction–to–Ambient – t ≤ 5 s	$R_{\theta JA}$	470	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).

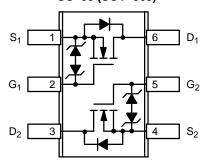


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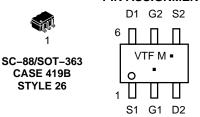
V _{(BR)DSS}	V _{(BR)DSS} R _{DS(on)} MAX	
60 V	1.6 Ω @ 10 V	300 mA
	2.5 Ω @ 4.5 V	300 IIIA

SC-88 (SOT-363)



Top View

MARKING DIAGRAM & PIN ASSIGNMENT



VTF = Device Code
M = Date Code
Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
NVJD5121NT1G	SC-88 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

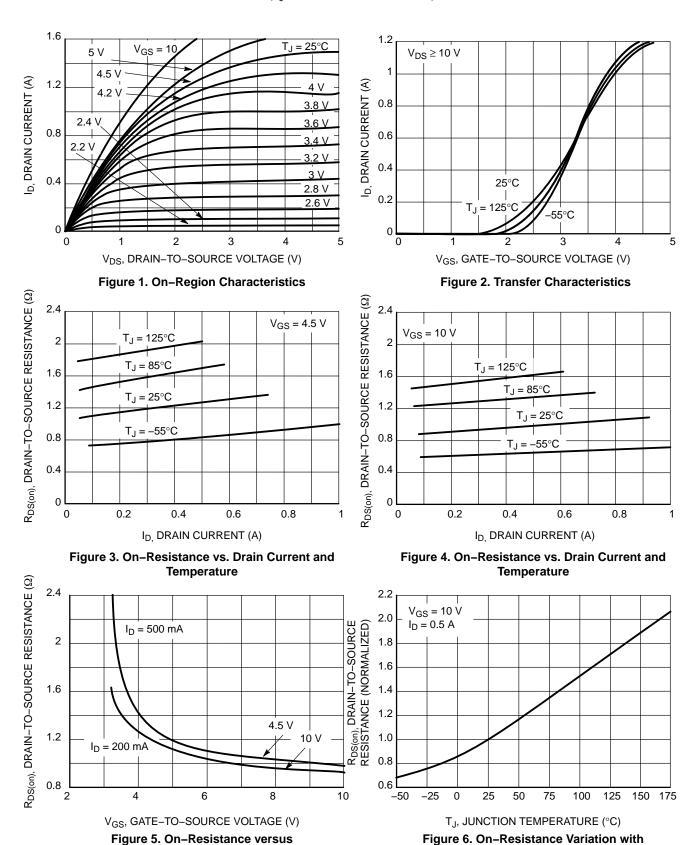
ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	· · · · · · · · · · · · · · · · · · ·		•		•	•	•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 250 μA, ref to 25°C			92		mV/°C
Zero Gate Voltage Drain Current	I_{DSS} $V_{GS} = 0 V$,		T _J = 25°C			1.0	μΑ
		$V_{DS} = 60 \text{ V}$	T _J = 125°C			500	7
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V				±10	μΑ
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D}$	= 250 μΑ	1.0	1.7	2.5	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				4.0		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 500 \text{ mA}$			1.0	1.6	Ω
		V _{GS} = 4.5 V, I _E	$V_{GS} = 4.5 \text{ V}, I_D = 200 \text{ mA}$		1.2	2.5	7
Forward Transconductance	9FS	V _{DS} = 5 V, I _D = 200 mA			80		S
Gate Resistance	R_{G}				536		Ω
CHARGES AND CAPACITANCES							
Input Capacitance	C _{ISS}	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = 20 \text{ V}$			26		pF
Output Capacitance	C _{OSS}				4.4		
Reverse Transfer Capacitance	C _{RSS}	- 503			2.5		
Total Gate Charge	$Q_{G(TOT)}$				0.9		nC
Threshold Gate Charge	$Q_{G(TH)}$	V _{GS} = 4.5 V, V	_{DS} = 25 V,		0.2		
Gate-to-Source Charge	Q_{GS}	$I_D = 200$	mA		0.3		
Gate-to-Drain Charge	Q_{GD}				0.28		
SWITCHING CHARACTERISTICS (No	ote 3)						
Turn-On Delay Time	t _{d(on)}				22		ns
Rise Time	t _r	V_{GS} = 4.5 V, V_{DD} = 25 V, I_{D} = 200 mA, R_{G} = 25 Ω			34		
Turn-Off Delay Time	t _{d(off)}				34		
Fall Time	t _f				32		
DRAIN-SOURCE DIODE CHARACTE	RISTICS						
Forward Diode Voltage	V_{SD}	$V_{GS} = 0 V$	T _J = 25°C		0.8	1.2	V
		$I_S = 200 \text{ mA}$	= 200 mA T _J = 85°C		0.7		7

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
2. Pulse Test: pulse width $\leq 300~\mu s$, duty cycle $\leq 2\%$.
3. Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES

(T_J = 25°C unless otherwise noted)



Temperature

Gate-to-Source Voltage

TYPICAL PERFORMANCE CURVES

 $(T_J = 25^{\circ}C \text{ unless otherwise noted})$

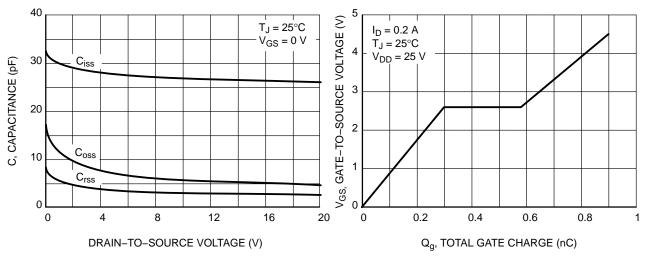


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

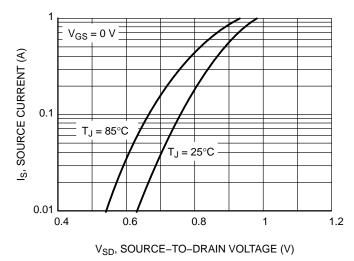
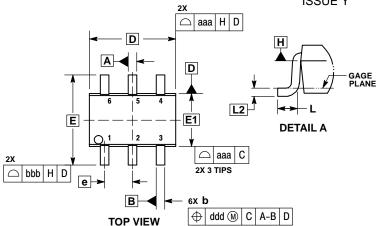


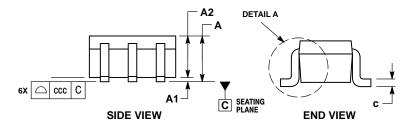
Figure 9. Diode Forward Voltage vs. Current

PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363

CASE 419B-02 ISSUE Y





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M. 1994.
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
 PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
 DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF
 THE PLASTIC BODY AND DATUM H.
 DATUMS A AND B ARE DETERMINED AT DATUM H.
 DIMENSIONS A AND CAPPLY TO THE ELAT SECTION OF THE
- DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
- DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 6 AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α			1.10			0.043
A1	0.00		0.10	0.000		0.004
A2	0.70	0.90	1.00	0.027	0.035	0.039
b	0.15	0.20	0.25	0.006	0.008	0.010
С	0.08	0.15	0.22	0.003	0.006	0.009
D	1.80	2.00	2.20	0.070	0.078	0.086
E	2.00	2.10	2.20	0.078	0.082	0.086
E1	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65 BSC			0.026 BSC		
L	0.26	0.36	0.46	0.010	0.014	0.018
L2	0.15 BSC			0.006 BSC		
aaa	0.15			0.006		
bbb	0.30			0.012		
000	0.40			0.004		

0.004

ddd STYLE 26:

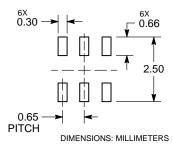
- PIN 1. SOURCE 1 2. GATE 1

0.10

RADIUS OF THE FOOT.

- DRAIN 2 SOURCE 2
- 5. GATE 2 6. DRAIN 1

RECOMMENDED SOLDERING FOOTPRINT



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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